Burn-In Sockets MPS Series OPEN TOP BGA SOCKET





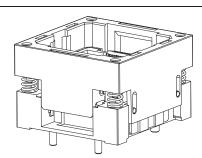
Open Top Style. Accommodates Chip Scale package with 1.0mm pitch. Compact size and low Actuation Force.

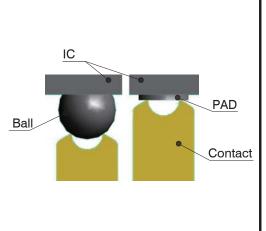
4-Point pinch design for enhanced electrical contact.

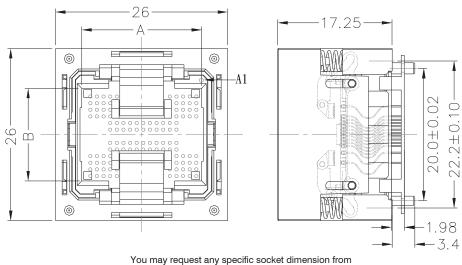
Field exchangeable package location plate.

"U" contact supports any type of solder ball shape and composition.





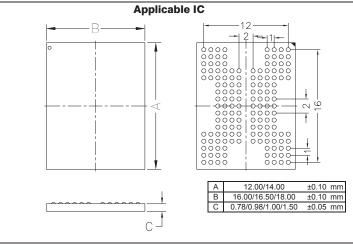




Contact Tip Detail

info@e-tec.com

For top view socket dimension
pls. ref. to separate catalog page



Specifications

Mechanical data

Contact life 25,000 cycles
Contact Normal Force 3-5g Per Pin
Operation Force 2.0Kg max.

Material

 Insulator
 (RoHS compliant)
 PES , PEI

 Contact
 (RoHS compliant)
 Beryllium Copper Alloy

 Contact plating
 Gold cover Nickel

Electrical data

 $\begin{array}{ll} \text{Contact resistance} & < 30 \text{ m}\Omega \\ \text{Current rating} & 1\text{A} \\ \text{Insulation resistance at 500V DC} & 1,000 \text{ m}\Omega \end{array}$

Operating temperature -55°C to +175°C

Recommendations:

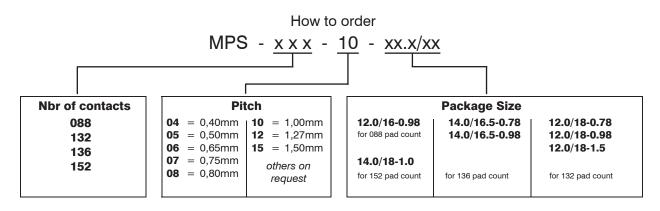
Solder paste – Please use a solder paste w/o any silver!

Solder profile - Please refer to our website www.e-tec.com

E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

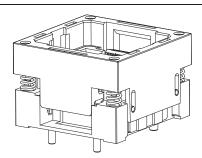


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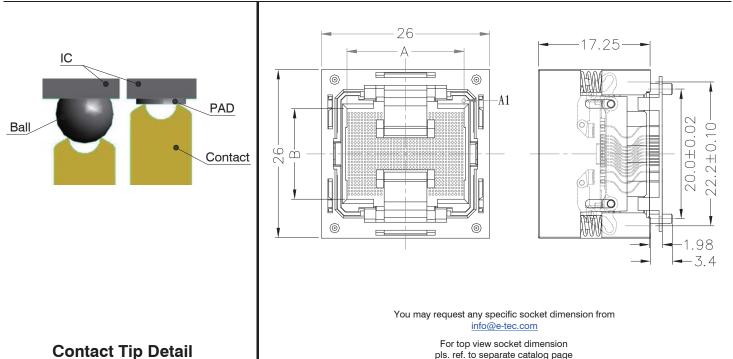




Open Top Style. Compact size and low Actuation Force. Accommodates BGA chip package with 0.50/0.65/0.80/1.00mm pitch. 4-Point pinch design for enhanced electrical contact. Unique mechanism to eliminate solder ball sticking. Field replaceable package location plate.



Please note, we will always request the chip data to ensure we offer a compatible socket.



Specifications

Mechanical data

25,000 cycles Contact life Contact Normal Force 3-5g Per Pin Operation Force 2.0kg min.

Material

Insulator (RoHS compliant) Contact (RoHS compliant)

PES, PEI Beryllium Copper Alloy Gold cover Nickel Contact plating

Electrical data

Contact resistance $< 30 \text{ m}\Omega$ Current rating Insulation resistance at 500V DC 1,000 mΩ

Operating temperature -55°C to +175°C

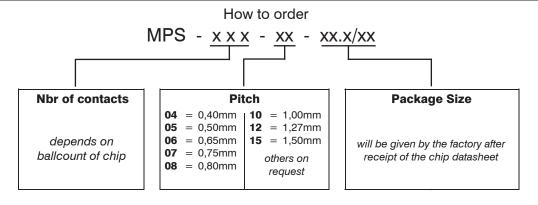
Recommendations:

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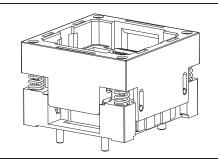


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Accommodates BGA chip package with 0.50/0.65/0.80/1.00mm pitch.
4-Point pinch design for enhanced electrical contact.
Unique mechanism to eliminate solder ball sticking.
Field replaceable package location plate.



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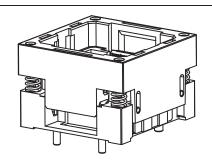
Pitch	No. of Contacts	Package Size(mm)	Part Number
0.5	40	8x9.2	MPS-040-05-8.0/9.2
	48	6x4	MPS-048-05-6.0/4
	56	6x6	MPS-056-05-6.0/6
	64	5x5	MPS-064-05-5.0/5
	84	6x6	MPS-084-05-6.0/6
	88	7x7	MPS-088-05-8.0/8
	105	6x6	MPS-105-05-6.0/6
	141	11.5x13	MPS-141-05-11.5/13
0.8	25	5x5	MPS-025-08-5.0/5
	30	5x5	MPS-030-08-5.0/5
	48	6x10	MPS-048-08-6.0/10
	48	6x11	MPS-048-08-6.0/11
	48	6x8	MPS-048-08-6.0/8
	48	6x9	MPS-048-08-6.0/9
	48	6.15x8.15	MPS-048-08-6.15/8.15
	48	8x10	MPS-048-08-8.0/10
	48	9x11	MPS-048-08-9.0/11
	48	9.5x12	MPS-048-08-9.5/12
	48	10.95x11.95	MPS-048-08-10.95/11.95
	48	11x12	MPS-048-08-11/12
	54	8x8	MPS-054-08-8.0/8
	56	7x9	MPS-056-08-7.0/9
	56	8x10	MPS-056-08-8.0/10
	56	8x11.6	MPS-056-08-8.0/11.6
	56	8x11.6	MPS-056-08-8/11.6
	56	8x13	MPS-056-08-8.0/13
	59	8x11.6	MPS-056-08-8.0/11.6
	60	8x10	MPS-060-08-8.0/10
	60	8x11.6	MPS-060-08-8.0/11.6
	60	11x13	MPS-060-08-11.0/13
	63	7x11	MPS-063-08-7.0/11
	64	7x7	MPS-064-08-7.0/7
	64	8x11	MPS-064-08-8.0/11
	64	8.1x11.1	MPS-064-08-8.1/11.1

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4-Point pinch design for enhanced electrical contact.
Unique mechanism to eliminate solder ball sticking.
Field replaceable package location plate.



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Pitch	No. of Contacts	Package Size(mm)	Part Number
1.0	64	7.95x8.95	MPS-064-10-7.95/8.95
	64	9x9	MPS-064-10-9.0/9
	64	9x11.5	MPS-064-10-9.0/11.5
	64	10.95x11.95	MPS-064-10-10.95/11.95
	66	7.47x11.02	MPS-066-10-7.47/11.02
	72	10x10	MPS-072-10-10.0/10
	80	7x9	MPS-080-10-7.0/09
	80	8x8	MPS-080-10-8.0/08
	80	8x10	MPS-080-10-8.0/10
	80	8x11	MPS-080-10-8.0/11
	80	9x11.5	MPS-080-10-9.0/11.5
	81	8x8	MPS-081-10-8.0/08
	81	14x18	MPS-081-10-14.0/18